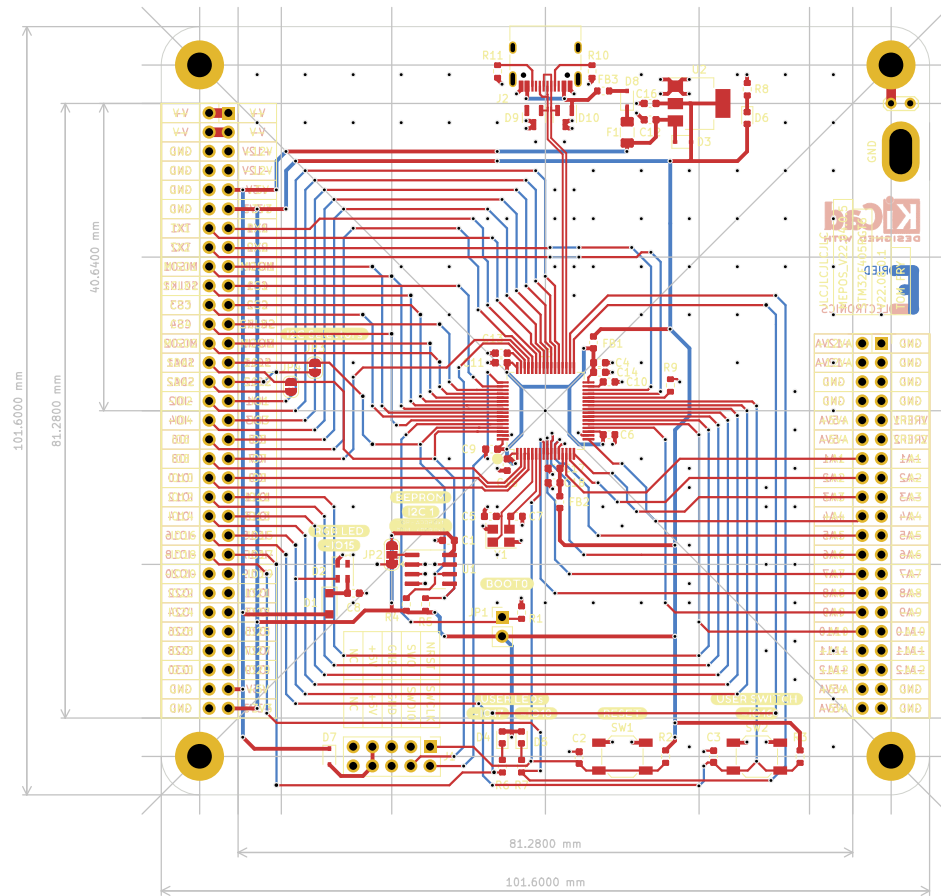


BACK



FRONT

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6062 mm
Board overall dimensions:	101.6000 mm x 101.6000 mm		
Min track/spacing:	0.2000 mm / 0.2000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	JLC7628	0.2104 mm		4.6	0.02
GND1.Cu	copper		0.0152 mm		1	0
Dielectric 2	core	FR4	1.065 mm		4.6	0.02
GND2.Cu	copper		0.0152 mm		1	0
Dielectric 3	prepreg	JLC7628	0.2104 mm		4.6	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

Sheet:
File: STM32F405RGT6.kicad_pcb

Title: STM32F405RGT6

Size: A4
KiCad E.D.A. kicad (6.0.5)

Date: 2022-08-30

Rev: V22.08.0.1

Id: 1/1